

MEGIC-00-012



March 13, 2002

Comp 2811
#3 / DS
3-29-02
estate

To: Commissioner of Patents and Trademarks
Washington, D.C. 20231

Fr: George O. Saile, Reg. No. 19,572
20 McIntosh Drive
Poughkeepsie, N.Y. 12603

RECEIVED
MAR 26 2002
TC 2800 MAIL ROOM

Subject:

Serial No. 09/821,546 03/30/01

Jin-Yuan Lee, Ching-Cheng Huang,
Mou-Shiang Lin

A STRUCTURE AND MANUFACTURING
METHOD OF CHIP SCALE PACKAGE

Grp. Art Unit: 2811

INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation
In An Application.

The following Patents and/or Publications are submitted to
comply with the duty of disclosure under CFR 1.97-1.99 and
37 CFR 1.56. Copies of each document is included herewith.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being
deposited with the United States Postal Service as first class
mail in an envelope addressed to: Commissioner of Patents and
Trademarks, Washington, D.C. 20231, on March 15, 2002.

Stephen B. Ackerman, Reg.# 37761

Signature/Date

Stephen B. Ackerman 3/15/02

U.S. Patent 6,064,114 to Higgins, III, "Semiconductor Device Having a Sub-Chip-Scale Package Structure and Method for Forming Same", discusses a semiconductor device having a sub-chip-scale package structure.

U.S. Patent 6,075,710 to Lau, "Low-Cost Surface-Mount Compatible Land-Grid Array (LGA) Chip Scale Package (CSP) for Packaging Solder-Bumped Flip Chips", discloses a novel electronic package.

The following five U.S. Patents disclose methods of making connections to chips:

- 1) U.S. Patent 5,994,766 to Shenoy et al., "Flip Chip Circuit Arrangement with Redistribution Layer that Minimizes Crosstalk.
- 2) U.S. Patent 6,118,183 to Umehara et al., "Semiconductor Device, Manufacturing Method Thereof, and Insulating Substrate for Same".
- 3) U.S. Patent 6,137,164 to Yew et al., "Thin Stacked Integrated Circuit Device".

- 4) U.S. Patent 5,734,201 to Djennas et al., "Low Profile Semiconductor Device with Like-Sized Chip and Mounting Substrate".
- 5) U.S. Patent 5,914,533 to Frech et al., "Multilayer Module with Thinfilm Redistribution Area".

Sincerely,

A handwritten signature in black ink, appearing to read 'SBA', with a stylized flourish extending to the right.

Stephen B. Ackerman,
Reg. No. 37761